# 2SK2958(L),2SK2958(S) 

## Silicon N Channel MOS FET <br> High Speed Power Switching

## HITACHI

## Features

- Low on-resistance
$\mathrm{R}_{\mathrm{DS}(\text { (on) })}=5.5 \mathrm{~m} \Omega$ typ.
- 4 V gate drive devices.
- High speed switching


## Outline



Absolute Maximum Ratings $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Ratings | Unit |
| :--- | :--- | :--- | :--- |
| Drain to source voltage | $\mathrm{V}_{\text {DSs }}$ | 30 | V |
| Gate to source voltage | $\mathrm{V}_{\text {Gss }}$ | $\pm 20$ | V |
| Drain current | $\mathrm{I}_{\mathrm{D}}$ | 75 | A |
| Drain peak current | $\mathrm{I}_{\text {(puuse) }}$ Note 1 | 300 | A |
| Body-drain diode reverse drain current | $\mathrm{I}_{\mathrm{DR}}$ | 75 | A |
| Channel dissipation | $\mathrm{Pch}^{\text {Note2 }}$ | 100 | W |
| Channel temperature | Tch | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

Note: 1. PW $\leq 10 \mu \mathrm{~s}$, duty cycle $\leq 1 \%$
2. Value at $\mathrm{Tc}=25^{\circ} \mathrm{C}$

Electrical Characteristics $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Drain to source breakdown voltage | $\mathrm{V}_{\text {(BR)OSS }}$ | 30 | - | - | V | $\mathrm{I}_{\mathrm{D}}=10 \mathrm{~mA}, \mathrm{~V}_{\mathrm{GS}}=0$ |
| Gate to source breakdown voltage | $\mathrm{V}_{\text {(BR)GSs }}$ | $\pm 20$ | - | - | V | $\mathrm{I}_{\mathrm{G}}= \pm 100 \mu \mathrm{~A}, \mathrm{~V}_{\mathrm{DS}}=0$ |
| Zero gate voltege drain current | $\mathrm{l}_{\text {DSS }}$ | - | - | 10 | $\mu \mathrm{A}$ | $\mathrm{V}_{\text {DS }}=30 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0$ |
| Gate to source leak current | $\mathrm{I}_{\text {Gss }}$ | - | - | $\pm 10$ | $\mu \mathrm{A}$ | $\mathrm{V}_{\mathrm{GS}}= \pm 16 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0$ |
| Gate to source cutoff voltage | $\mathrm{V}_{\mathrm{GS} \text { (oft) }}$ | 1.0 | - | 2.0 | V | $\mathrm{I}_{\mathrm{D}}=1 \mathrm{~mA}, \mathrm{~V}_{\text {DS }}=10 \mathrm{~V}$ |
| Static drain to source on state resistance | $\mathrm{R}_{\text {DS(on) }}$ | - | 5.5 | 7.0 | $\mathrm{m} \Omega$ | $\mathrm{I}_{\mathrm{D}}=40 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}^{\text {Note3 }}$ |
| Static drain to source on state resistance | $\mathrm{R}_{\text {DS(on) }}$ | - | 9.0 | 14.0 | $\mathrm{m} \Omega$ | $\mathrm{I}_{\mathrm{D}}=40 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=4 \mathrm{~V}^{\text {Note3 }}$ |
| Forward transfer admittance | $\left\|y_{\text {ts }}\right\|$ | 35 | 60 | - | S | $\mathrm{I}_{\mathrm{D}}=40 \mathrm{~A}, \mathrm{~V}_{\mathrm{DS}}=10 \mathrm{~V}^{\text {Note3 }}$ |
| Input capacitance | Ciss | - | 4100 | - | pF | $V_{\text {DS }}=10 \mathrm{~V}$ |
| Output capacitance | Coss | - | 2700 | - | pF | $\mathrm{V}_{\mathrm{GS}}=0$ |
| Reverse transfer capacitance | Crss | - | 800 | - | pF | $\mathrm{f}=1 \mathrm{MHz}$ |
| Turn-on delay time | $\mathrm{t}_{\mathrm{d}(0 n)}$ | - | 45 | - | ns | $\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=40 \mathrm{~A}$ |
| Rise time | $\mathrm{t}_{\mathrm{r}}$ | - | 430 | - | ns | $\mathrm{R}_{\mathrm{L}}=0.25 \Omega$ |
| Turn-off delay time | $\mathrm{t}_{\text {d(off) }}$ | - | 460 | - | ns |  |
| Fall time | $\mathrm{t}_{\mathrm{f}}$ | - | 440 | - | ns |  |
| Body-drain diode forward voltage | $\mathrm{V}_{\mathrm{DF}}$ | - | 1.0 | - | V | $\mathrm{I}_{\mathrm{F}}=75 \mathrm{~A}, \mathrm{~V}_{\text {GS }}=0$ |
| Body-drain diode reverse recovery time | $\mathrm{t}_{\text {r }}$ | - | 90 | - | ns | $\begin{aligned} & \mathrm{I}_{\mathrm{F}}=75 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0 \\ & \mathrm{diF} / \mathrm{dt}=50 \mathrm{~A} / \mathrm{\mu s} \end{aligned}$ |

Note: 3. Pulse test

## Main Characteristics




Typical Output Characteristics



Static Drain to Source on State Resistance


Static Drain to Source on State Resistance vs. Drain Current


Forward Transfer Admittance vs. Drain Current







Normalized Transient Thermal Impedance vs. Pulse Width


Switching Time Test Circuit


Waveform


## Package Dimensions

Unit: mm


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